

HIGH-SIDE MEASUREMENT CURRENT SHUNT MONITOR

Check for Samples: [INA139-Q1](#), [INA169-Q1](#)

FEATURES

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Complete Unipolar High-Side Current Measurement Circuit
- Wide Supply and Common-Mode Ranges
 - INA139-Q1: 2.7 V to 40 V
 - INA169-Q1: 2.7 V to 60 V
- Independent Supply and Input Common-Mode Voltages
- Single Resistor Gain Set
- Low Quiescent Current (60 μ A Typ)
- Wide Temperature Range: -40°C to $+125^{\circ}\text{C}$
- TSSOP-8 Package

APPLICATIONS

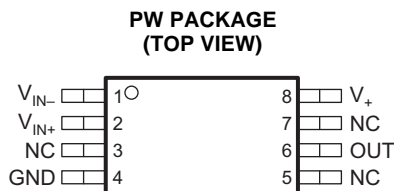
- Current Shunt Measurement:
 - Automotive, Telephone, Computers
- Portable And Battery-Backup Systems
- Battery Chargers
- Power Management
- Cell Phones
- Precision Current Source

DESCRIPTION

The INA139 and INA169 are high-side, unipolar, current shunt monitors. Wide input common-mode voltage range, high-speed, low quiescent current, and tiny TSSOP-8 packaging enable use in a variety of applications.

The device converts a differential input voltage to a current output. This current is converted back to a voltage with an external load resistor that sets any gain from 1 to over 100. Although designed for current shunt measurement, the circuit invites creative applications in measurement and level shifting.

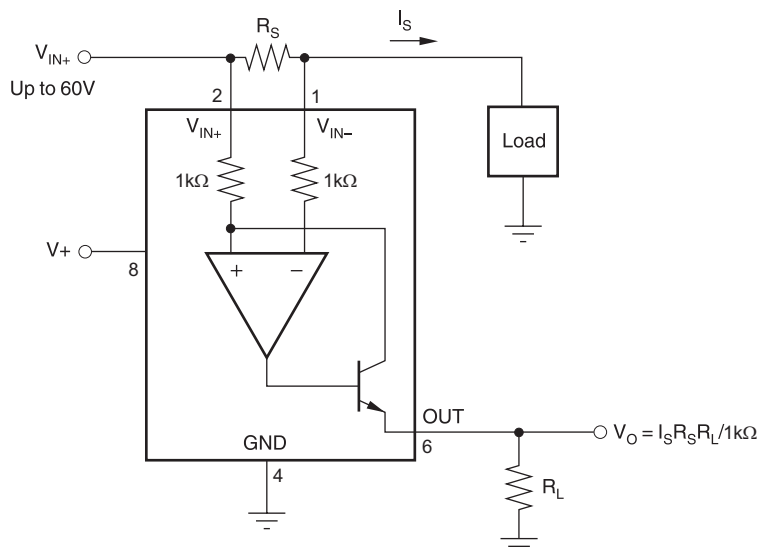
Both the INA139 and INA169 are available in TSSOP-8 and are specified for the -40°C to 125°C temperature range.



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE ⁽²⁾	PACKAGE MARKING	TRANSPORT MEDIA, QUANTITY
INA139QPWRQ1	TSSOP-8	PW	–40°C to 125°C	INA139	Tape and Reel, 2000
INA169QPWRQ1	TSSOP-8	PW	–40°C to 125°C	INA169	Tape and Reel, 2000

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_+	INA139	–0.3 V to 60 V
	INA169	–0.3 V to 75 V
Analog input voltage range, V_{IN+} , V_{IN-} , Common mode	INA139	–0.3 V to 60 V
	INA169	–0.3 V to 75 V
Analog input voltage range, $(V_{IN+}) - (V_{IN-})$, Differential		–40 V to 2 V
Analog output range, out		–0.3 V to 40 V
Operating temperature range		–55°C to 125°C
Storage temperature range		–65°C to 150°C
Maximum junction temperature		150°C
Thermal resistance, junction-to-ambient, $R_{\theta JA}$		150°C/W
Lead temperature (soldering, 10 seconds)		260°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

$T_A = -40^{\circ}\text{C}$ to 125°C , $V_S = 5\text{ V}$, $V_{IN+} = 12\text{ V}$, and $R_{OUT} = 25\text{ k}\Omega$ unless otherwise noted

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
INPUT						
Full-scale sense voltage	$V_{\text{SENSE}} = V_{\text{IN}+} - V_{\text{IN}-}$			100	500	mV
Common-mode input range ($V_{\text{IN}+}$)		INA139	2.7		40	V
		INA169	2.7		60	
Common-mode rejection	$V_{\text{IN}+} = 2.7\text{ V to }40\text{ V}$, $V_{\text{SENSE}} = 50\text{ mV}$	INA139	100	115		dB
	$V_{\text{IN}+} = 2.7\text{ V to }60\text{ V}$, $V_{\text{SENSE}} = 50\text{ mV}$	INA169	100	120		
Offset voltage ⁽¹⁾ RTI				±0.2	±2	mV
Offset voltage vs temperature				1		µV/°C
Offset voltage vs power supply, V_+	$V_{\text{IN}+} = 2.7\text{ V to }40\text{ V}$, $V_{\text{SENSE}} = 50\text{ mV}$	INA139		0.5	10	µV/V
	$V_{\text{IN}+} = 2.7\text{ V to }60\text{ V}$, $V_{\text{SENSE}} = 50\text{ mV}$	INA169		0.1	10	
Input bias current				10		µA
OUTPUT						
Transconductance	$V_{\text{SENSE}} = 10\text{ mV to }150\text{ mV}$		980	1000	1020	µA/V
Transconductance vs temperature	$V_{\text{SENSE}} = 100\text{ mV}$			10		nA/°C
Nonlinearity error	$V_{\text{SENSE}} = 10\text{ mV to }150\text{ mV}$			±0.01%	±0.2%	
Total output error	$V_{\text{SENSE}} = 100\text{ mV}$			±0.5%	±2%	
Output impedance					1	GΩ
					5	pF
Voltage output swing to power supply, V_+				(V_+) - 0.9	(V_+) - 1.2	V
Voltage output swing to common mode, V_{CM}				$V_{\text{CM}} - 0.6$	$V_{\text{CM}} - 1$	V
FREQUENCY RESPONSE						
Bandwidth		$R_{\text{OUT}} = 10\text{ k}\Omega$		440		kHz
		$R_{\text{OUT}} = 20\text{ k}\Omega$		220		
Settling time (0 1%)	5 V step	$R_{\text{OUT}} = 10\text{ k}\Omega$		2.5		µs
		$R_{\text{OUT}} = 20\text{ k}\Omega$		5		
NOISE						
Output-current noise density				20		pA/√Hz
Total output-current noise	BW = 100 kHz			7		nA RMS
POWER SUPPLY						
Operating range, V_+		INA139	2.7		40	V
		INA169	2.7		60	
Quiescent current	$V_{\text{SENSE}} = 0$, $I_{\text{O}} = 0$			60	125	µA

(1) Defined as the amount of input voltage, V_{SENSE} , to drive the output to zero.

TYPICAL CHARACTERISTICS

Typical characteristics are at $T_A = 25^\circ\text{C}$, $V_+ = 5\text{ V}$, $V_{IN+} = 12\text{ V}$, and $R_L = 125\text{ k}\Omega$, unless otherwise noted.

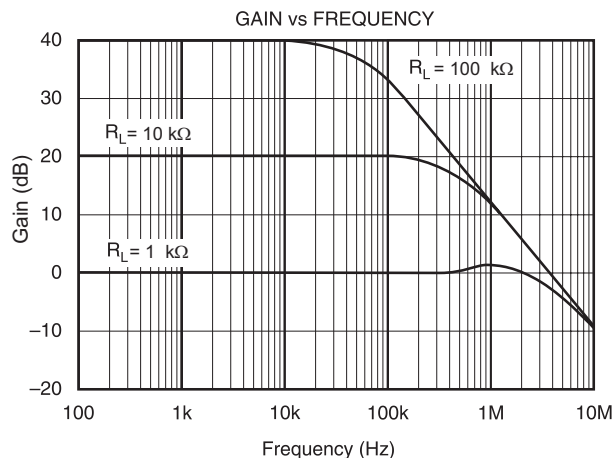


Figure 1.

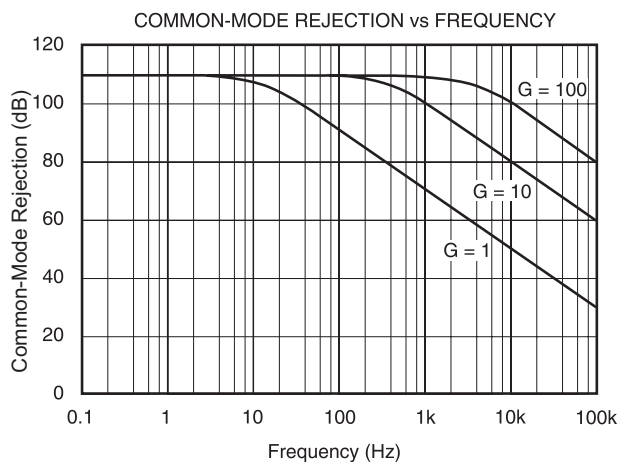


Figure 2.

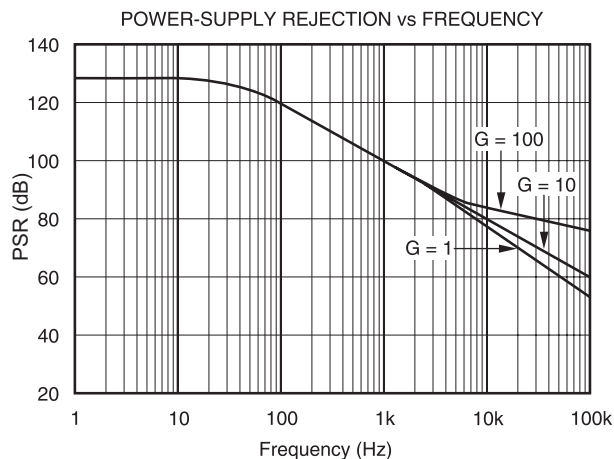


Figure 3.

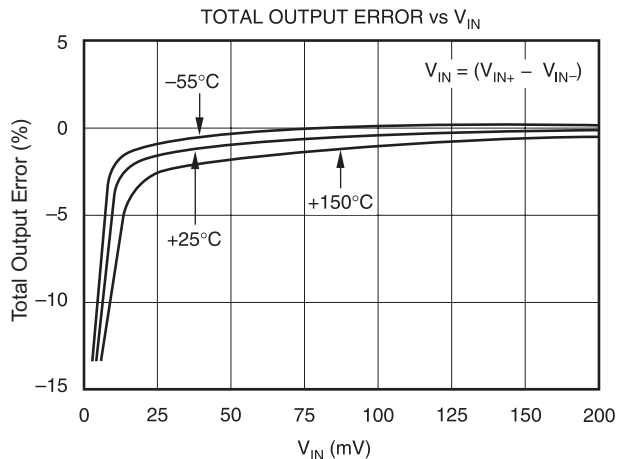


Figure 4.

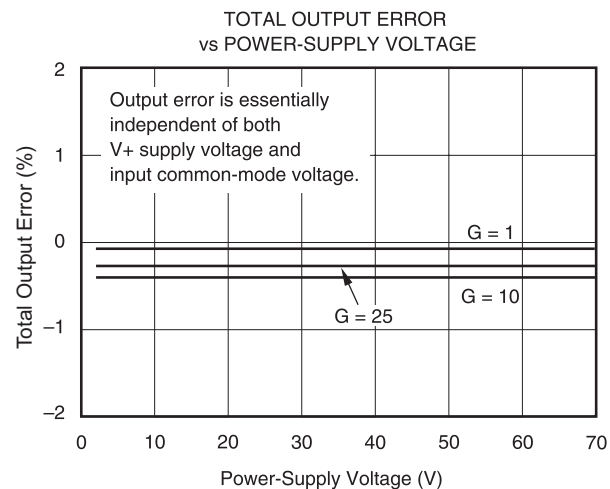


Figure 5.

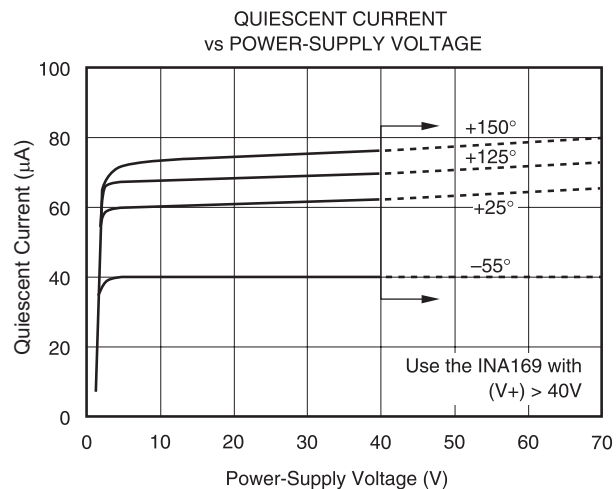


Figure 6.

TYPICAL CHARACTERISTICS (continued)

Typical characteristics are at $T_A = 25^\circ\text{C}$, $V_+ = 5\text{ V}$, $V_{IN+} = 12\text{ V}$, and $R_L = 125\text{ k}\Omega$, unless otherwise noted.

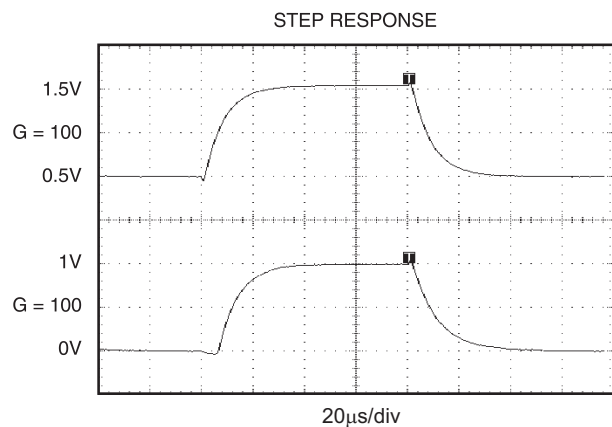


Figure 7.

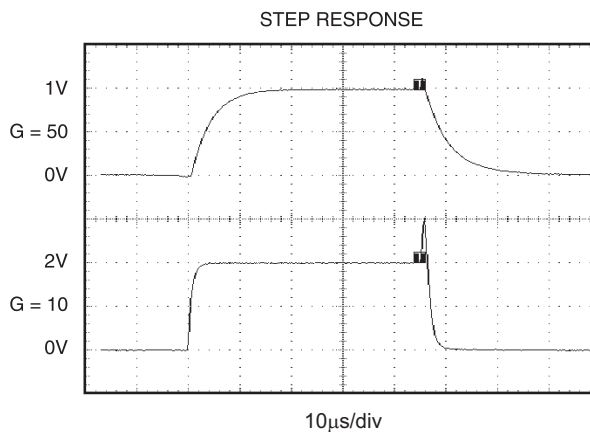


Figure 8.

APPLICATION INFORMATION

Figure 9 illustrates the basic circuit diagram for both the INA139 and INA169. Load current I_S is drawn from supply V_S through shunt resistor R_S . The voltage drop in shunt resistor V_S is forced across R_{G1} by the internal operational amplifier, causing current to flow into the collector of Q1. External resistor R_L converts the output current to a voltage, V_{OUT} , at the OUT pin.

The transfer function for the INA139 is:

$$I_O = g_m (V_{IN+} - V_{IN-}) \text{ where } g_m = 1000 \mu\text{A/V}.$$

In the circuit of Figure 9, the input voltage ($V_{IN+} - V_{IN-}$) is equal to $I_S \times R_S$ and the output voltage (V_{OUT}) is equal to $I_O \times R_L$. The transconductance (g_m) of the INA139 is 1000 $\mu\text{A/V}$. The complete transfer function for the current measurement amplifier in this application is:

$$V_{OUT} = (I_S) (R_S) (1000 \mu\text{A/V}) (R_L)$$

The maximum differential input voltage for accurate measurements is 0.5 V, which produces a 500- μA output current. A differential input voltage of up to 2 V will not cause damage. Differential measurements (pins 3 and 4) must be unipolar with a more-positive voltage applied to pin 3. If a more-negative voltage is applied to pin 3, the output current, I_O , will be zero, but it will not cause damage.

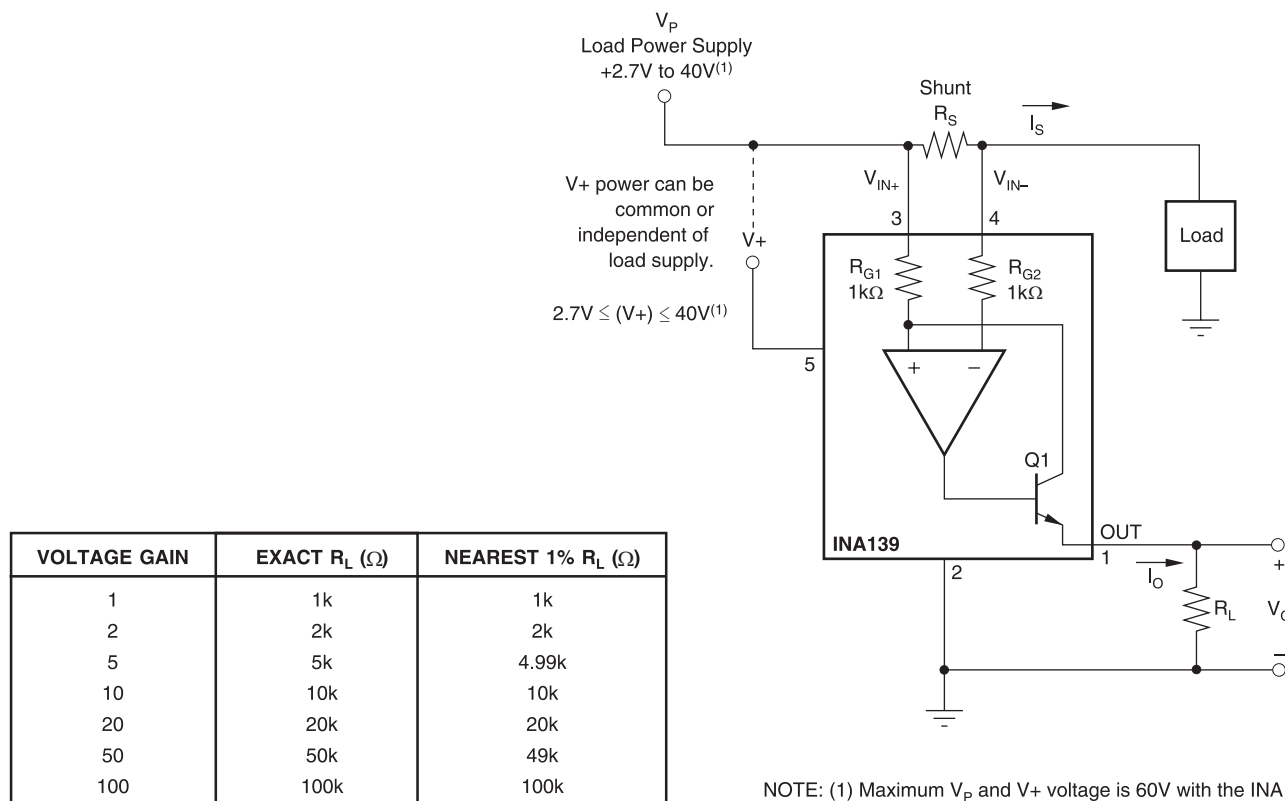


Figure 9. Basic Circuit Connections

BASIC CONNECTION

Figure 9 shows the basic connection of the INA139. The input pins, V_{IN+} and V_{IN-} , should be connected as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance. The output resistor, R_L , is shown connected between pin 1 and ground. Best accuracy is achieved with the output voltage measured directly across R_L . This is especially important in high-current systems where load current could flow in the ground connections, affecting the measurement accuracy.

No power-supply bypass capacitors are required for stability of the INA139. However, applications with noisy or high-impedance power supplies may require decoupling capacitors to reject power-supply noise; connect bypass capacitors close to the device pins.

APPLICATIONS

The INA139 is designed for current shunt measurement circuits, as shown in Figure 9, but its basic function is useful in a wide range of circuitry. A few ideas are illustrated in Figure 12 through Figure 15.

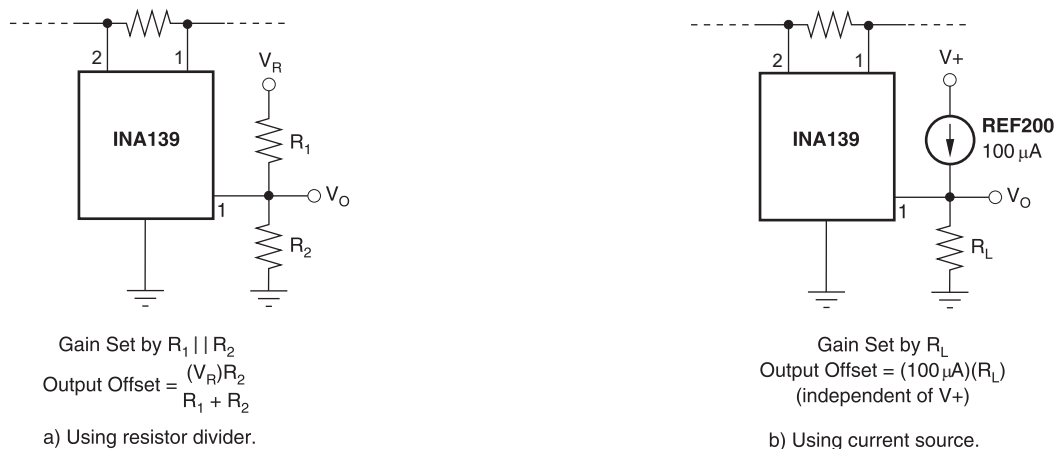


Figure 12. Offsetting the Output Voltage

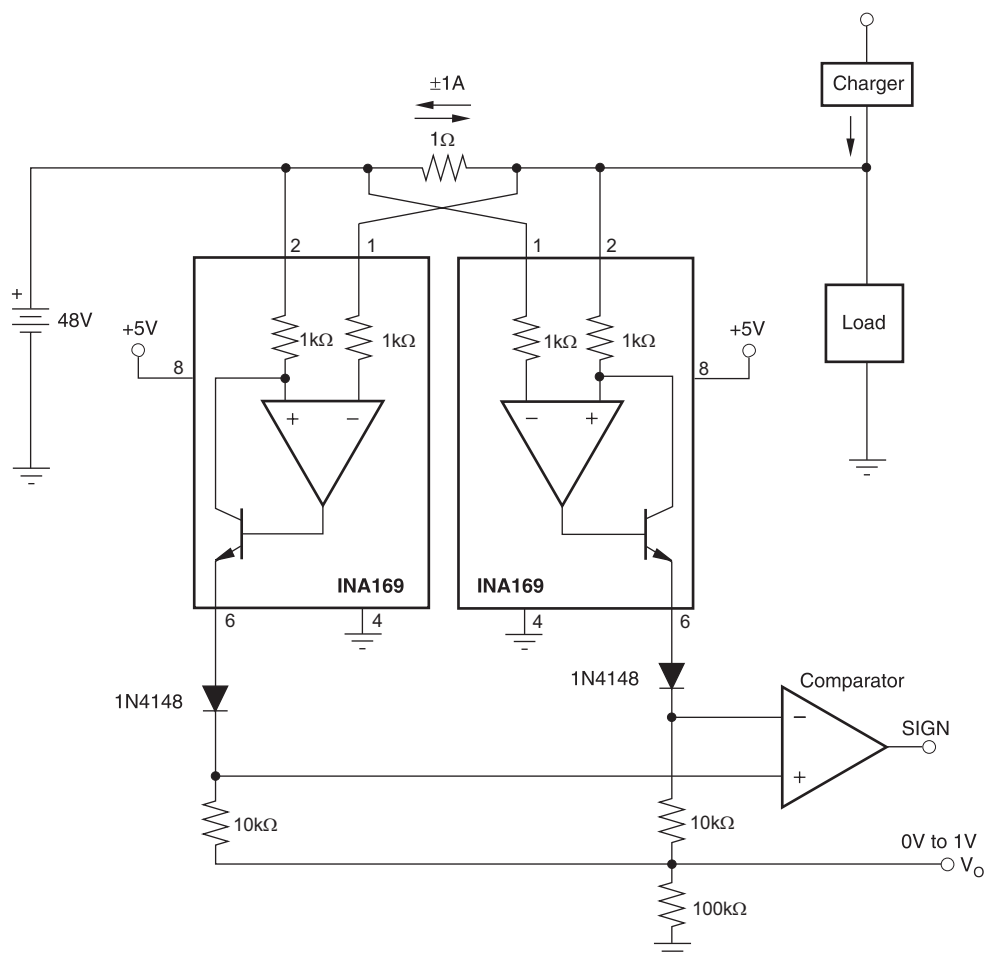


Figure 13. Bipolar Current Measurement

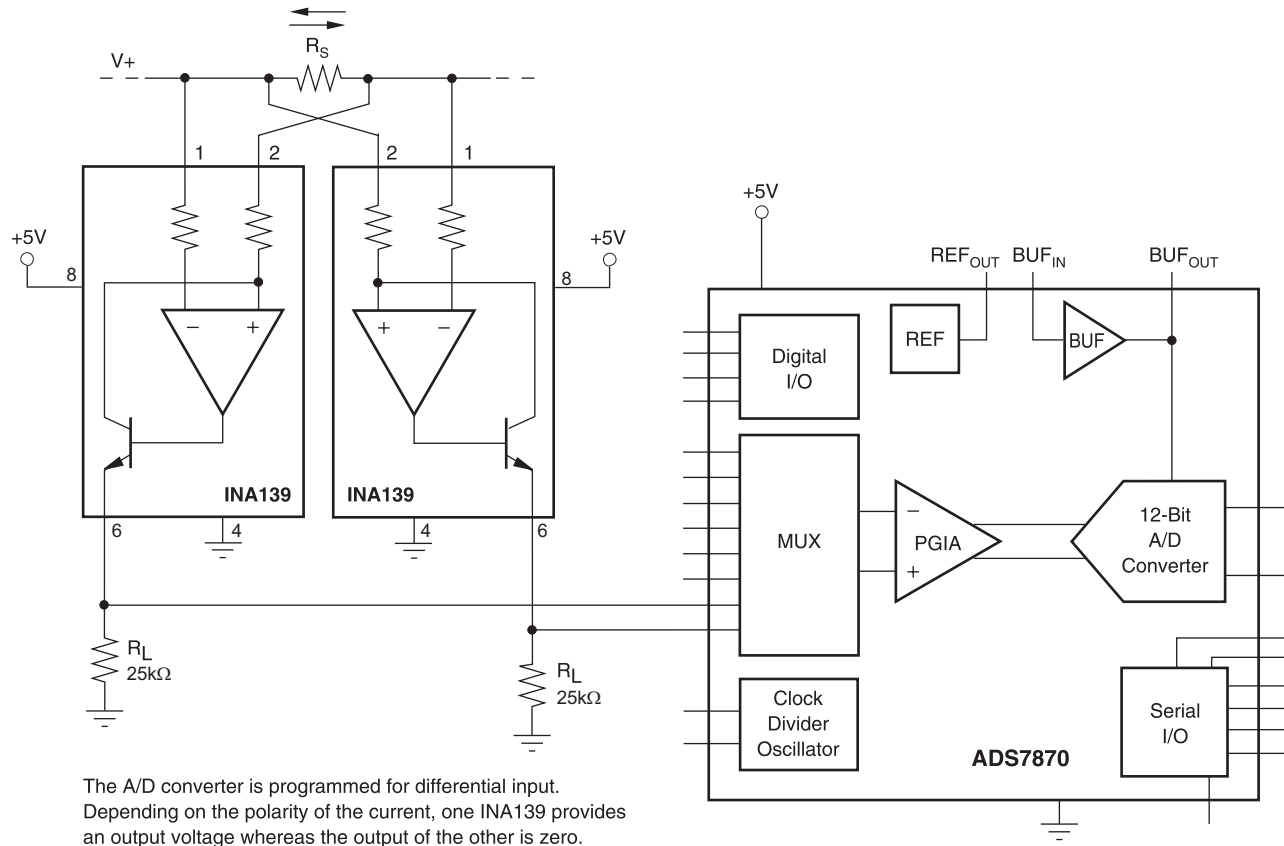


Figure 14. Bipolar Current Measurement Using Differential Input of A/D Converter

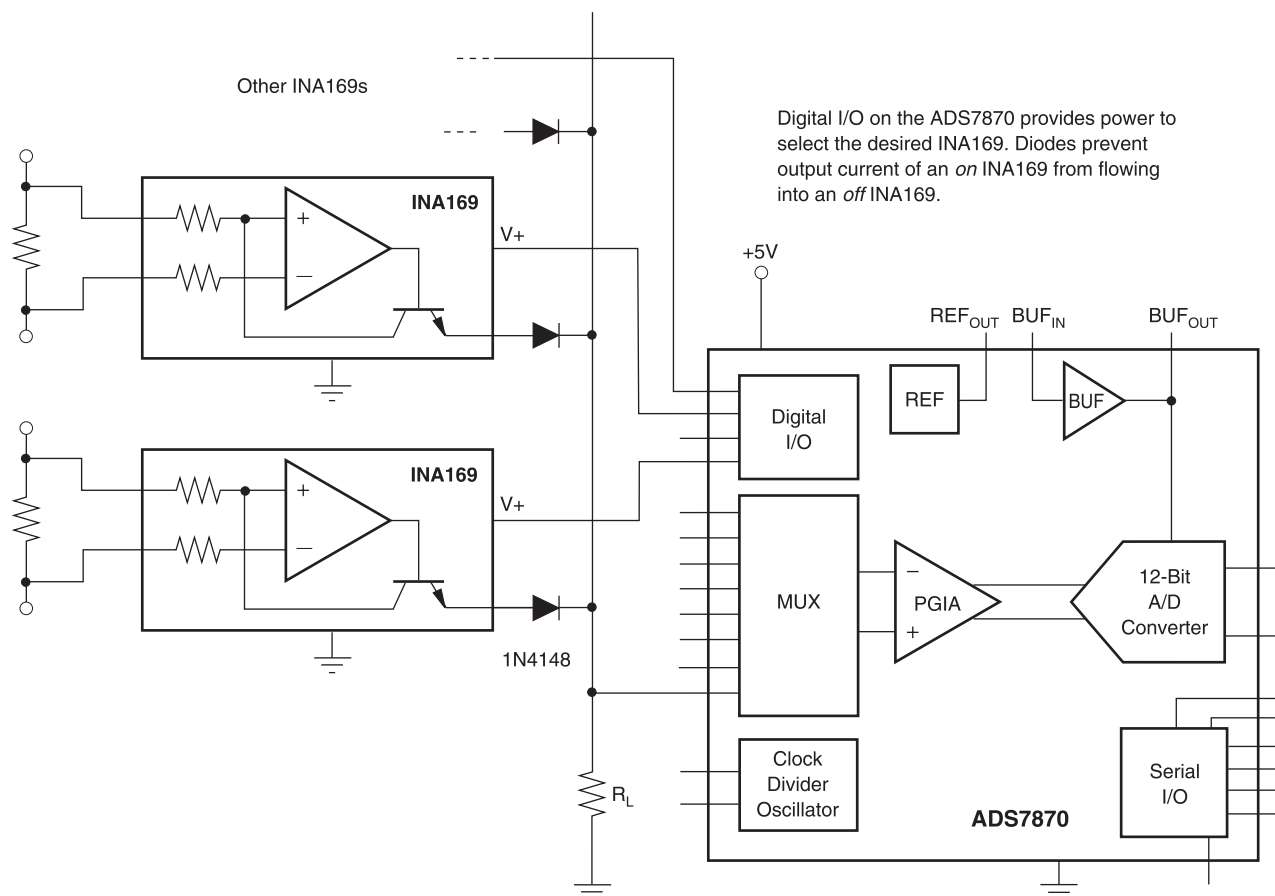


Figure 15. Multiplexed Measurement Using Logic Signal for Power

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
INA139QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	INA139	Samples
INA139QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	INA139	Samples
INA169QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	INA169	Samples
INA169QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	INA169	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF INA139-Q1, INA169-Q1 :

- Catalog: [INA139](#), [INA169](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

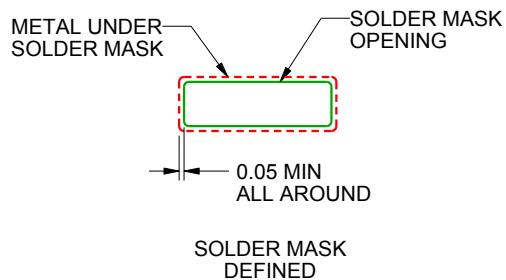
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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